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FIG. 1

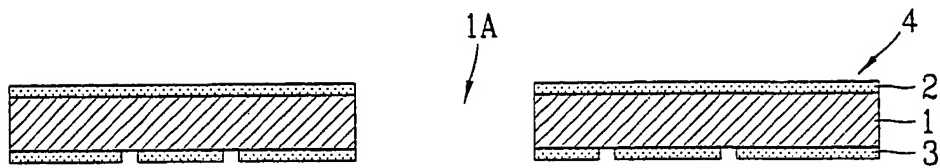


FIG. 2

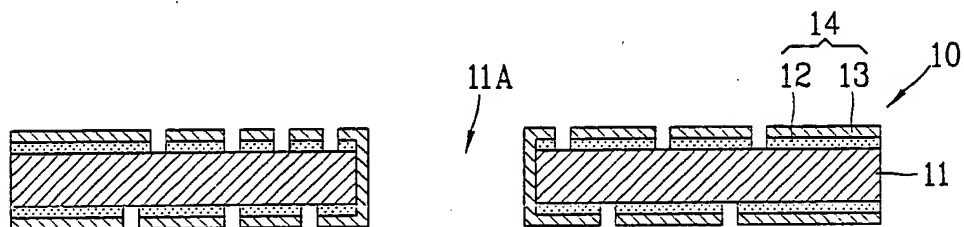


FIG. 3

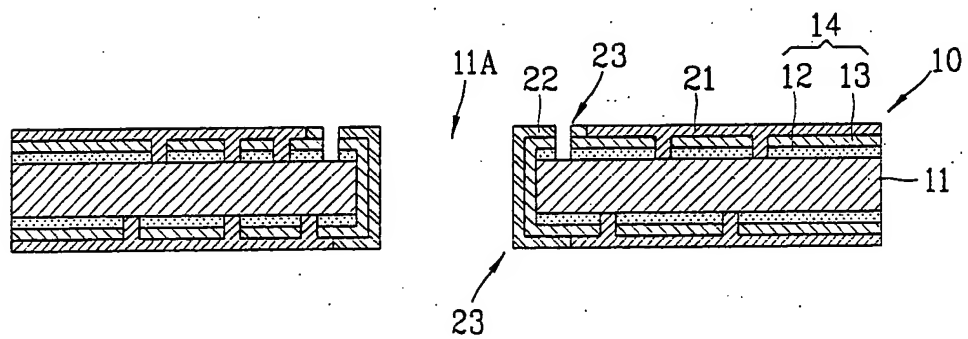


FIG. 4

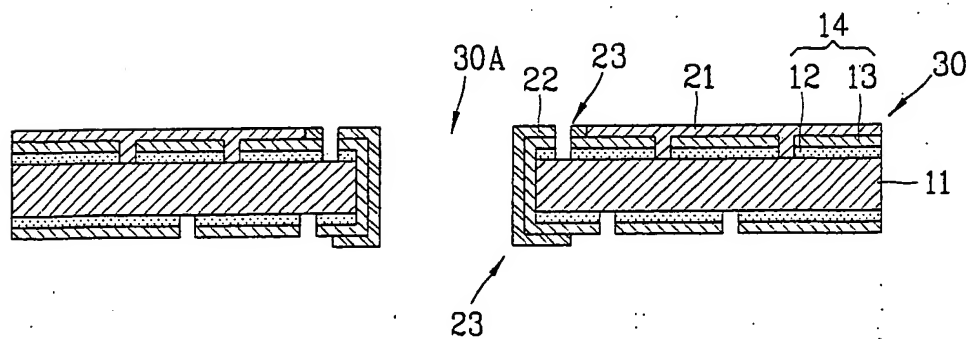


FIG. 5

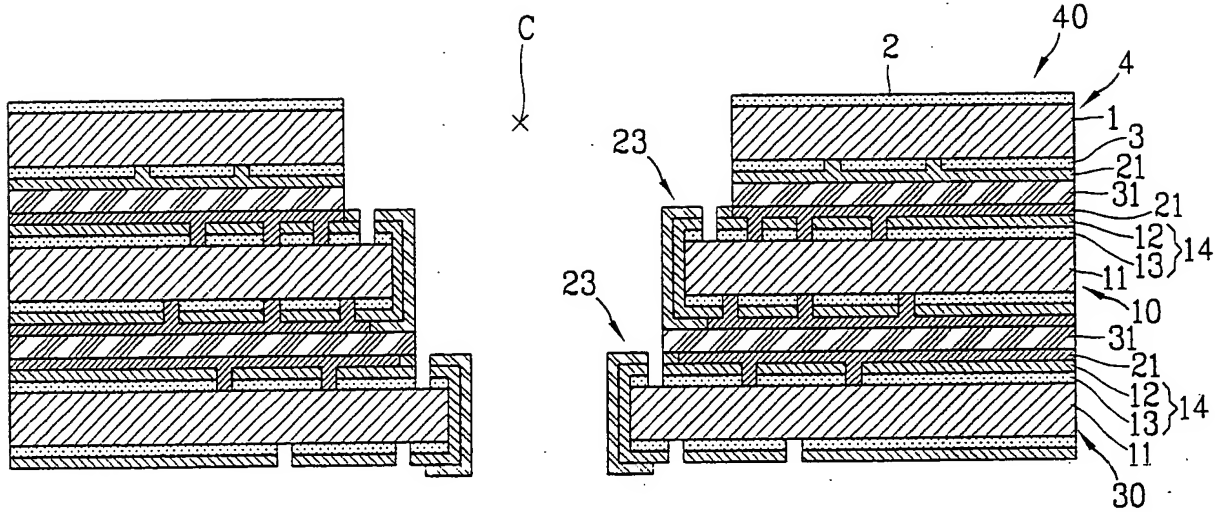


FIG. 6

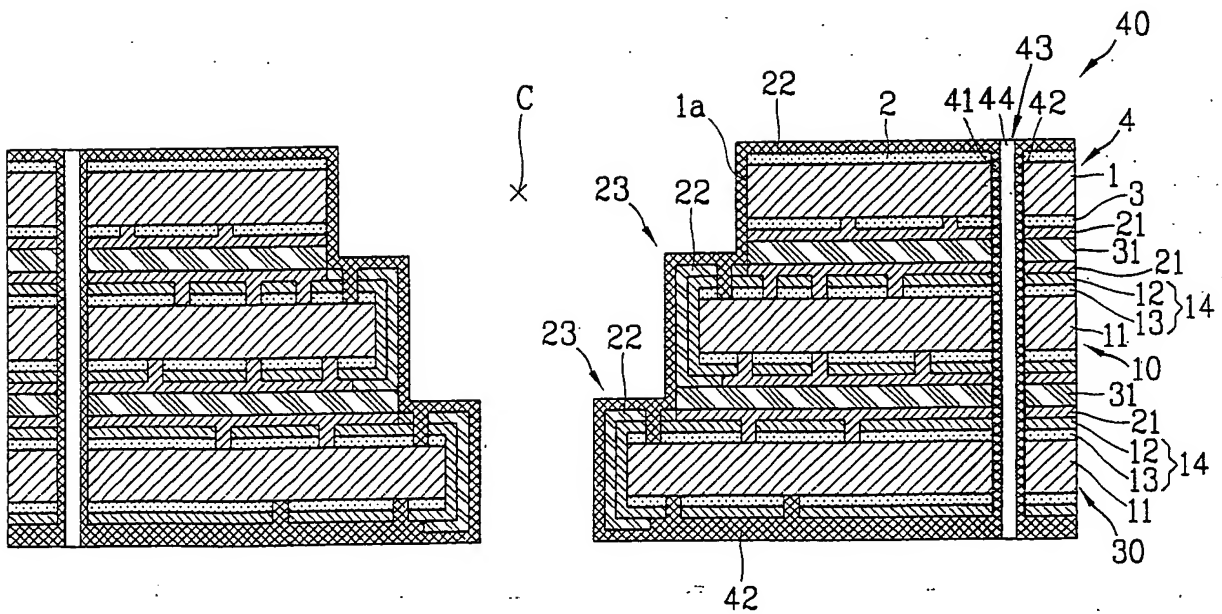




FIG. 9

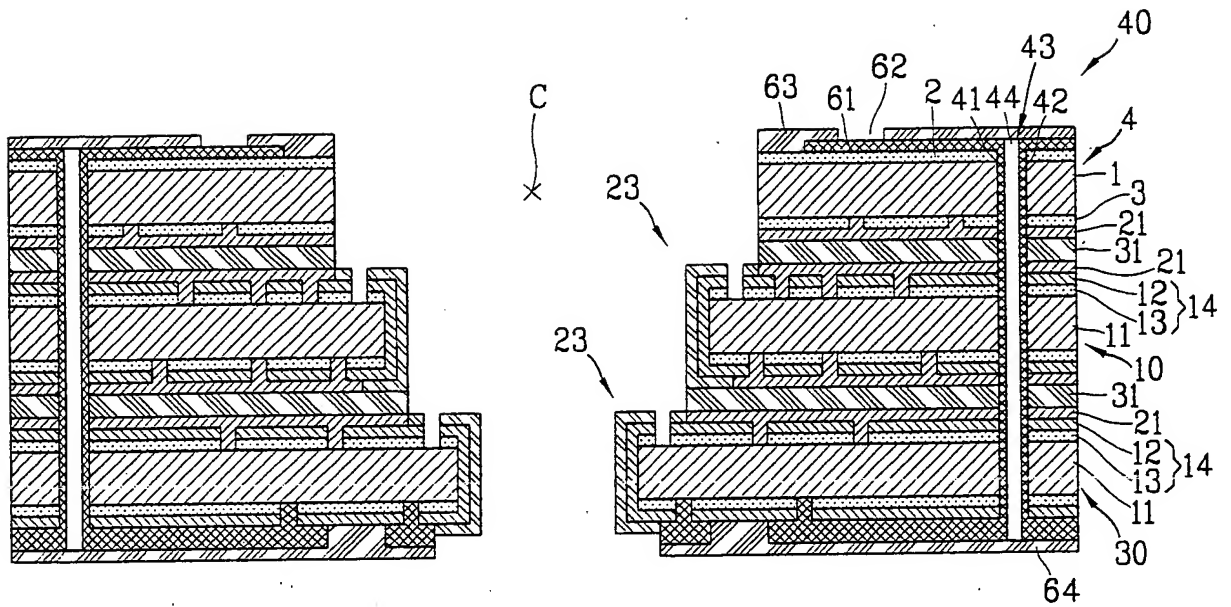
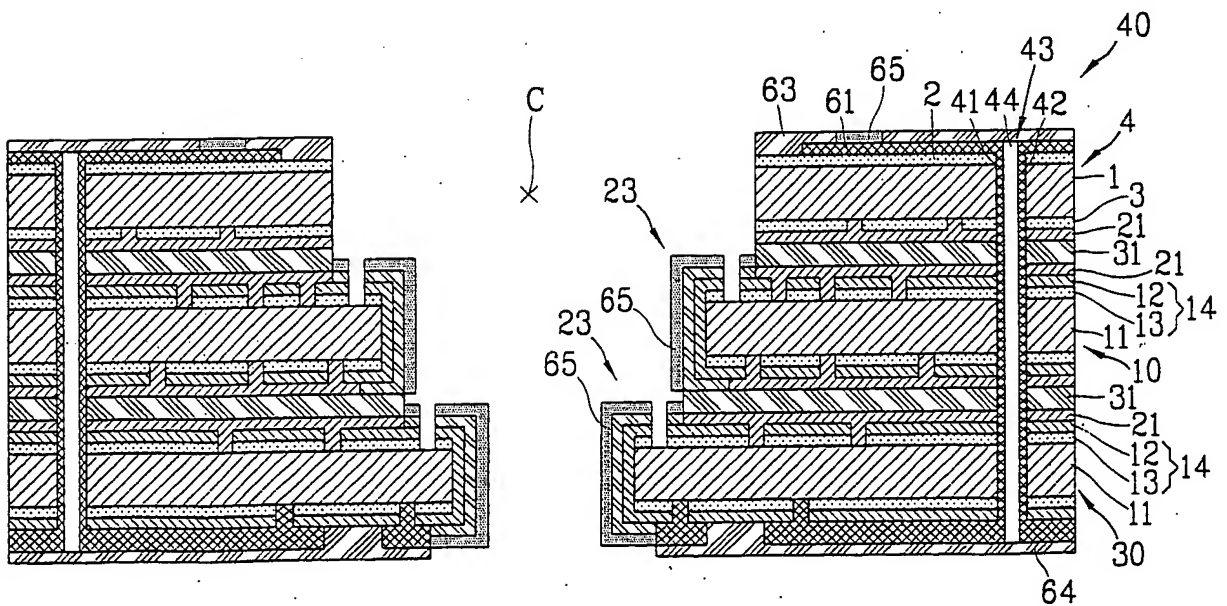


FIG. 10



This diagram shows a cross-section of a semiconductor device along line C-C'. It features a substrate 83 with various layers including 64, 82, 30, 11, 13, 12, 21, 31, 10, 14, 4, and 1. A central component 81 is surrounded by layers 71, 65, 61, 2, 41, 44, and 42. Other labeled parts include 23, 65, 66, 43, and 100.

FIG. 13

